SPIE. PHOTONICS WEST

Okamoto Corporation

Invites you to: SPIE Photonics West
When: February 4-6, 2020
Where: Moscone Center-Booth 3451

Grinding/Polishing/Lapping/Slicing

Comprehensive Abrasive Solutions for a Multitude of Materials

5 proven solutions for your Wafer Thinning Process demands:

Package Grinding

Grinding technology for:

- Cu + mold , FOPLP. FOWLP
- TSV: Cu + Si

Next Generation Power Devices

Low-damage and high-speed processing technologies and equipment for SiC & GaN.

BG Tape Grinding

Full -automated system for standard back grinding and bumped wafer technologies.

TSV

Cutting edge technology for Via Middle. TTV adjustment and contamination elimination

Electrical Components

Grinding and Polishing capabilities for electrical components such as LT and LN.

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